

8th CIES Technology Forum VIRTUAL

March 27 (Mon) – 28 (Tue), 2023

Progress Report

27 March (Mon) **DAY1**

http://www.cies.tohoku.ac.jp/8th_forum/

Part 1 [Live] 9:00-12:00 (JST)

9:00-9:05	Welcome address President, Tohoku Univ.	Hideo Ohno (Tohoku Univ.)
	Address Chairperson, Executive Board, TIA	Tetsuro Higashi (TIA)
	Address Director-General, Research and Development Bureau, MEXT	Yoshiyuki Chihara (MEXT)
9:05-9:30	Address Deputy Director-General, Industrial Science and Technology Policy and Environment Bureau, METI	Tetsuya Tanaka (METI)
	Address Director-General, Patent Examination Department (Electronic Technology), JPO	Shinichi Omori (JPO)
9:30-10:00	CIES Overview	Tetsuo Endoh (Tohoku Univ.)
10:00-10:20	Industry-academic collaboration STT-MRAM Aimed at Developing Non-Volatile Working Memory and its Manufacturing Technologies	Shoji Ikeda (Tohoku Univ.)
10:20-10:35	Industry-academic collaboration Supersensitive Magnetic Sensors using Ferromagnetic Tunnel Junctions	Yasuo Ando (Tohoku Univ.)
10:35-10:50	Industry-academic collaboration Embedded Security Technology	Naofumi Homma (Tohoku Univ.)
10:50-11:10	MEXT X-nics Innovative Spintronics X Semiconductor Research Hub	Tetsuo Endoh (Tohoku Univ.)
11:10-11:25	NEDO Post-5G Microfabrication Core Technologies for Nonvolatile MRAM at 1.5nm Node and Beyond	Shoji Ikeda (Tohoku Univ.)
11:25-11:40	NEDO AIC Efficient Design and Demonstration of AI Processor using CMOS / Spintronics Hybrid Technology	Takahiro Hanyu (Tohoku Univ.)
11:40-11:55	MEXT INNOPEL (Innovative Power Electronics Technologies) Integrated Power Electronics for the Realization of a Decarbonized Society	Yoshikazu Takahashi (Tohoku Univ.)
11:55-12:00	Closing Remarks	Tetsuo Endoh (Tohoku Univ.)

Part 2 [Streaming] 17:00-19:30 (JST)

17:00-17:30	CIES Overview	Tetsuo Endoh (Tohoku Univ.)
17:30-17:50	Industry-academic collaboration STT-MRAM Aimed at Developing Non-Volatile Working Memory and its Manufacturing Technologies	Shoji Ikeda (Tohoku Univ.)
17:50-18:05	Industry-academic collaboration Supersensitive Magnetic Sensors using Ferromagnetic Tunnel Junctions	Yasuo Ando (Tohoku Univ.)
18:05-18:20	Industry-academic collaboration Embedded Security Technology	Naofumi Homma (Tohoku Univ.)
18:20-18:40	MEXT X-nics Innovative Spintronics X Semiconductor Research Hub	Tetsuo Endoh (Tohoku Univ.)
18:40-18:55	NEDO Post-5G Microfabrication Core Technologies for Nonvolatile MRAM at 1.5nm Node and Beyond	Shoji Ikeda (Tohoku Univ.)
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19:25-19:30	Closing Remarks	Tetsuo Endoh (Tohoku Univ.)

Organizer: Center for Innovative Integrated Electronic Systems (CIES), Tohoku Univ.

Co-sponsored: Research Institute of Electrical Communication (RIEC), Tohoku Univ.

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